



### **General Description**

The WST3400Dis the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WST3400D meet the RoHS and Green Product requirement with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

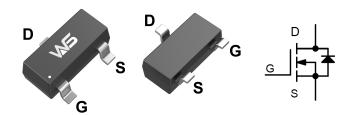
#### **Product Summery**

BVDSS	RDSON	ID
20V	45mΩ	3.2A

## **Applications**

- High Frequency Point-of-Load Synchronous s Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

### **SOT-23N Pin Configuration**



## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
$V_{DS}$	Drain-Source Voltage	20	V	
$V_{GS}$	Gate-Source Voltage	±12	V	
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup>	3.2	А	
I <sub>D</sub> @T <sub>C</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup>	2.0	А	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	10	Α	
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation <sup>3</sup>	1.0	W	
T <sub>STG</sub>	Storage Temperature Range -55 to 150		$^{\circ}$	
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	$^{\circ}$	

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>		200	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		75	°C/W



# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	20			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃, I <sub>D</sub> =1mA		0.024		V/°C
	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =1.8A		45	55	mΩ
R <sub>DS(ON)</sub>		V <sub>GS</sub> =2.5V , I <sub>D</sub> =1.5A		55	65	
		V <sub>GS</sub> =1.8V , I <sub>D</sub> =1A		70	90	
$V_{GS(th)}$	Gate Threshold Voltage	V -V 1 -250uA	0.3	0.85	1.2	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-2.51		mV/℃
	Drain Source Lookage Current	V <sub>DS</sub> =16V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			1	
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =16V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			5	- uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 8V$ , $V_{DS}$ = $0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =3A		10		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.7	3.4	Ω
$Q_g$	Total Gate Charge (4.5V)			6.4		
$Q_{gs}$	Gate-Source Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =1A		0.54		nC
$Q_gd$	Gate-Drain Charge			1.25		
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}$ =10V , $V_{GS}$ =4.5V , $R_{G}$ =3.3 $\Omega$		1.6		
Tr	Rise Time			29.6		
T <sub>d(off)</sub>	Turn-Off Delay Time			18.8		ns
T <sub>f</sub>	Fall Time			6		
Ciss	Input Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		382		
C <sub>oss</sub>	Output Capacitance			41		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			33		

## **Diode Characteristics**

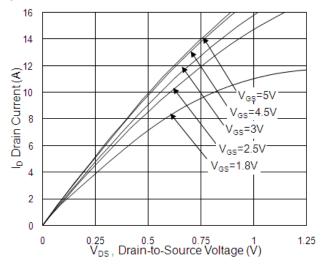
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,4</sup>	V =V =0V Force Current			3.2	А
I <sub>SM</sub>	Pulsed Source Current <sup>2,4</sup>	$V_G=V_D=0V$ , Force Current			10	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25℃			1.2	V
t <sub>rr</sub>	Reverse Recovery Time			5.5		nS
Q <sub>rr</sub>	Reverse Recovery Charge	IF=2A , dI/dt=100A/ $\mu$ s , T $_{J}$ =25 $^{\circ}$ C		1.8		nC

#### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper ,t<10sec.
- 2.The data tested by pulsed , pulse width  $\,\leq\,$  300us , duty cycle  $\,\leq\,$  2%
- 3.The power dissipation is limited by 150  $^{\circ}\mathrm{C}$  junction temperature
- 4. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



# **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

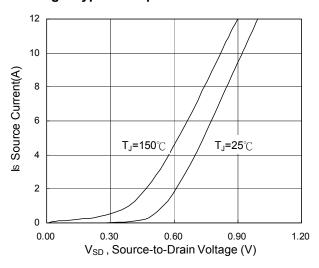


Fig.3 Forward Characteristics Of Reverse

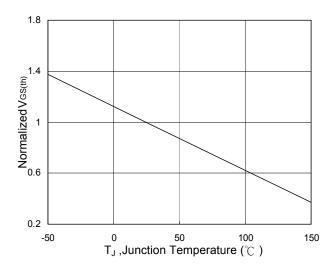


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$ 

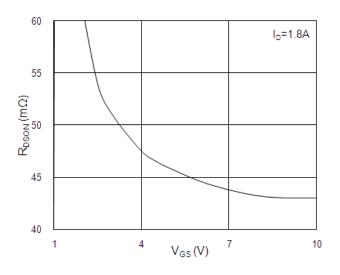


Fig.2 On-Resistance vs. Gate-Source

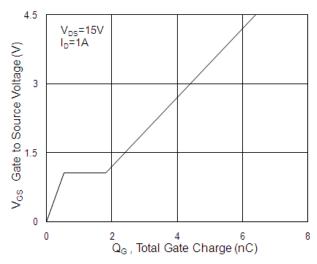


Fig.4 Gate-Charge Characteristics

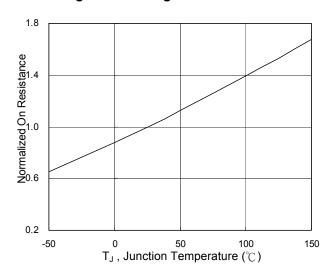
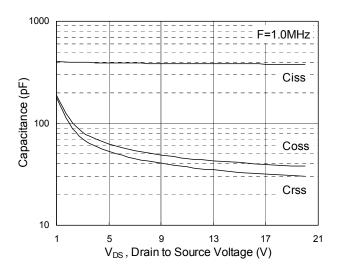


Fig.6 Normalized  $R_{\text{DSON}}$  vs.  $T_{\text{J}}$ 





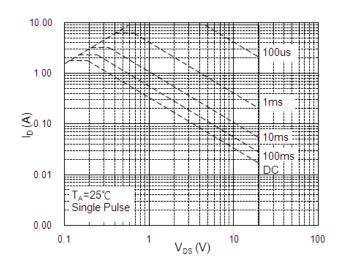


Fig.7 Capacitance

Fig.8 Safe Operating Area

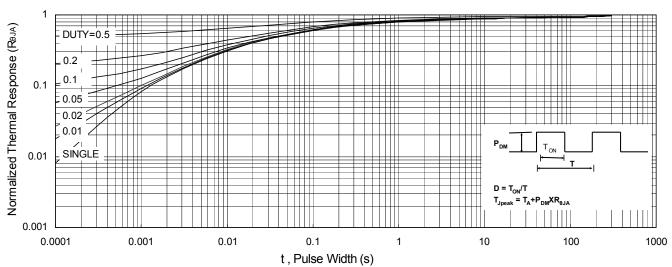
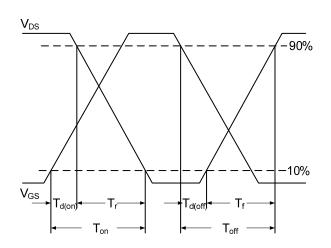


Fig.9 Normalized Maximum Transient Thermal Impedance





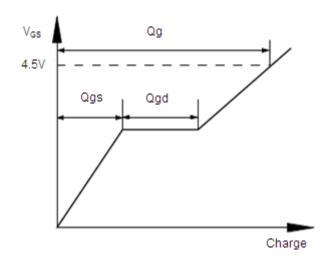


Fig.11 Gate Charge Waveform



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DMN1017UCP3-7 EFC2J004NUZTDG P85W28HP2F-7071 DMN1053UCP4-7 NTE2384 DMC2700UDMQ-7 DMN2080UCB4-7
DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B IPS60R3K4CEAKMA1 DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 IPS60R360PFD7SAKMA1
DMN2990UFB-7B SSM3K35CT,L3F IPLK60R1K0PFD7ATMA1 2N7002W-G MCAC30N06Y-TP IPWS65R035CFD7AXKSA1
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